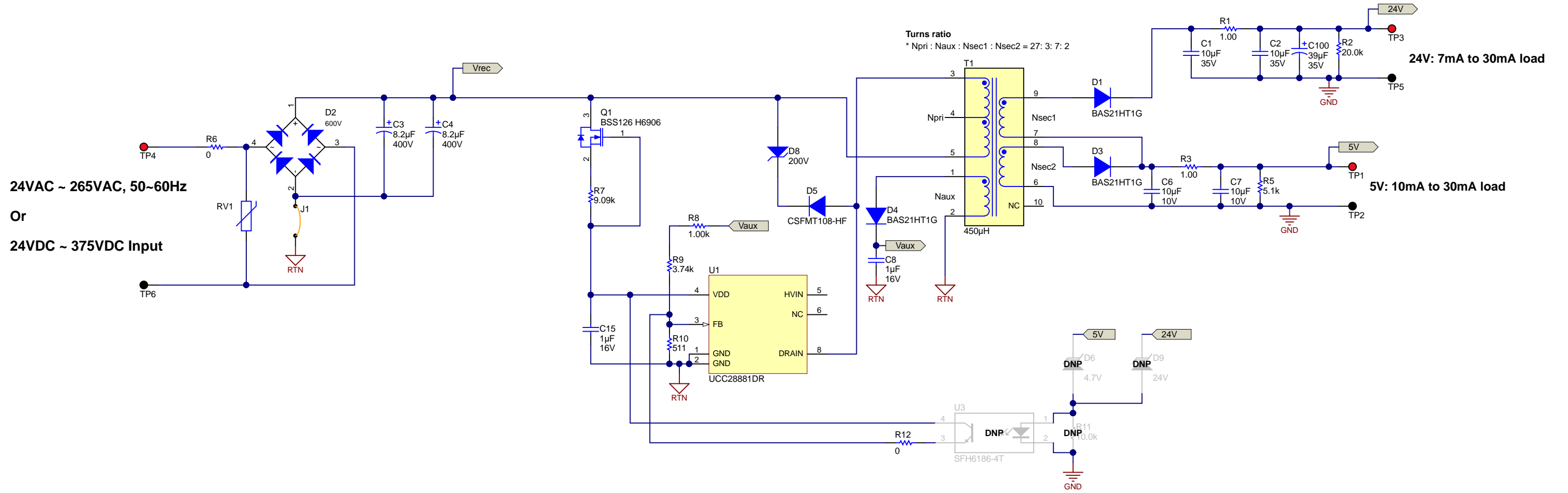


Design Notes

1. C100 is an add-on item.



PCB Number: PMP20708
 PCB Rev: A

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TID #: N/A	Project Title: Wide Vin PSR Flyback	
Number: PMP20708	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 1
Drawn By:	File: PMP20708_BlankSheet.SchDoc	Size: B
Engineer: Sheng-Yang Yu	Contact: http://www.ti.com/support	



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